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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of:

Fung Leng Chen, et al. Docket No.: TI-25912  
Serial No.: 09/115,444 Examiner: Dinh, Tuan T.  
Filed: 07/14/98 Art Unit: 2827  
For: High Density Internal Ball Grid Array Integrated Circuit Package

**Amendment under 37 CFR 1.111**

Assistant Commissioner of Patents  
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)  
I hereby certify that this correspondence is being deposited with  
the U.S. Postal Service as First Class Mail in an envelope addressed  
to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

5-5-03

Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 02/04/03. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.